

# μESD3.3DT5G SERIES

## ESD Protection Diodes

### In Ultra Small SOT-723 Package

The μESD Series is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications.

#### Specification Features:

- Small Body Outline Dimensions:  
0.047" x 0.032" (1.20 mm x 0.80 mm)
- Low Body Height: 0.020" (0.5 mm)
- Stand-off Voltage: 3.3 V – 6.0 V
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection
- These are Pb-Free Devices

#### Mechanical Characteristics:

**CASE:** Void-free, transfer-molded, thermosetting plastic  
Epoxy Meets UL 94 V-0

**LEAD FINISH:** 100% Matte Sn (Tin)

**MOUNTING POSITION:** Any

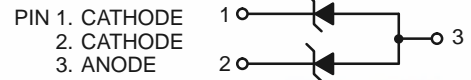
**QUALIFIED MAX REFLOW TEMPERATURE:** 260°C

Device Meets MSL 1 Requirements

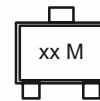


ON Semiconductor®

<http://onsemi.com>



#### MARKING DIAGRAM



xx = Device Code  
M = Date Code

#### ORDERING INFORMATION

Device	Package	Shipping†
μESDxxDT5G	SOT-723	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air Contact		±30 ±30	kV
IEC 61000-4-4 (EFT)		40	A
ESD Voltage Per Human Body Model Per Machine Model		16 400	kV V
Total Power Dissipation on FR-5 Board (Note 1) @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	240 1.9	mW mW/°C
Thermal Resistance Junction-to-Ambient	R <sub>θJA</sub>	525	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	T <sub>L</sub>	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-5 = 1.0 x 0.75 x 0.62 in.

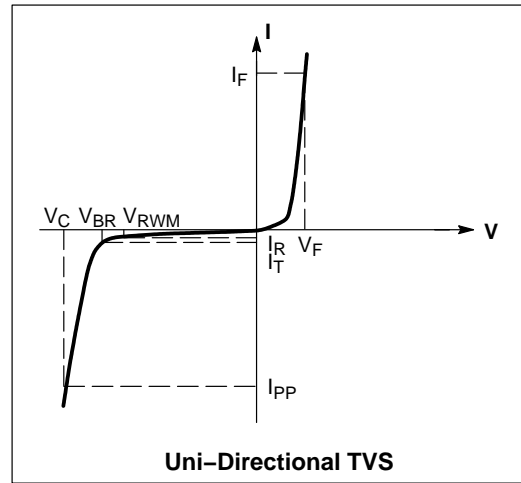


## μESD3.3DT5G SERIES

### ELECTRICAL CHARACTERISTICS

(T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current
V <sub>C</sub>	Clamping Voltage @ I <sub>PP</sub>
V <sub>RWM</sub>	Working Peak Reverse Voltage
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>
I <sub>T</sub>	Test Current
I <sub>F</sub>	Forward Current
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>
P <sub>pk</sub>	Peak Power Dissipation
C	Max. Capacitance @ V <sub>R</sub> = 0 and f = 1 MHz



### ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted, V<sub>F</sub> = 0.9 V Max. @ I<sub>F</sub> = 10 mA for all types)

Device*	Device Marking	V <sub>RWM</sub> (V)	I <sub>R</sub> (μA) @ V <sub>RWM</sub>	V <sub>BR</sub> (V) @ I <sub>T</sub> (Note 2)	I <sub>T</sub>	C (pF)
		Max	Max	Min	mA	Typ
μESD3.3DT5G	L0	3.3	1.0	5.0	1.0	47
μESD5.0DT5G	L2	5.0	0.1	6.2	1.0	38
μESD6.0DT5G	L3	6.0	0.1	7.0	1.0	34

\*Other voltages available upon request.

2. V<sub>BR</sub> is measured with a pulse test current I<sub>T</sub> at an ambient temperature of 25°C.

# $\mu$ ESD3.3DT5G SERIES

## TYPICAL CHARACTERISTICS

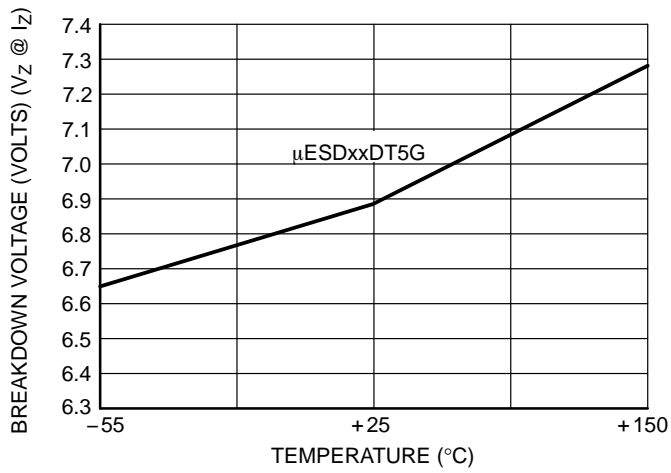


Figure 1. Typical Breakdown Voltage versus Temperature

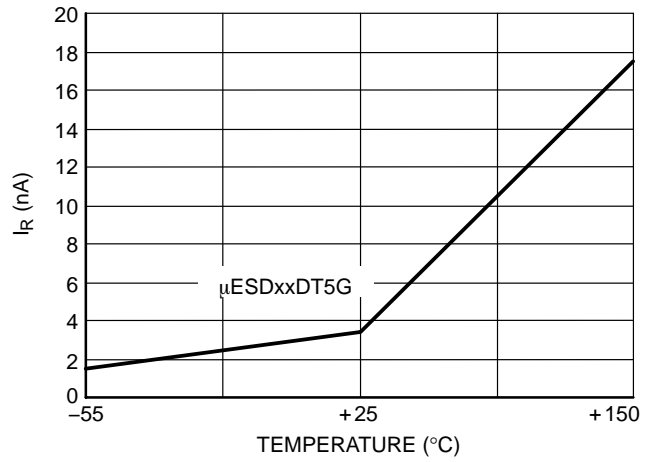


Figure 2. Typical Leakage Current versus Temperature

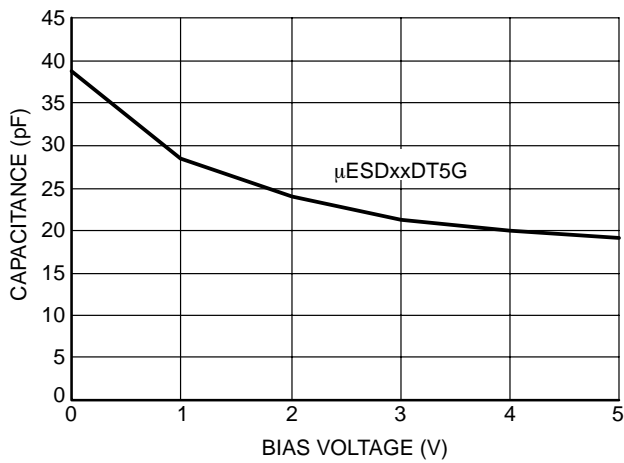


Figure 3. Typical Capacitance versus Bias Voltage

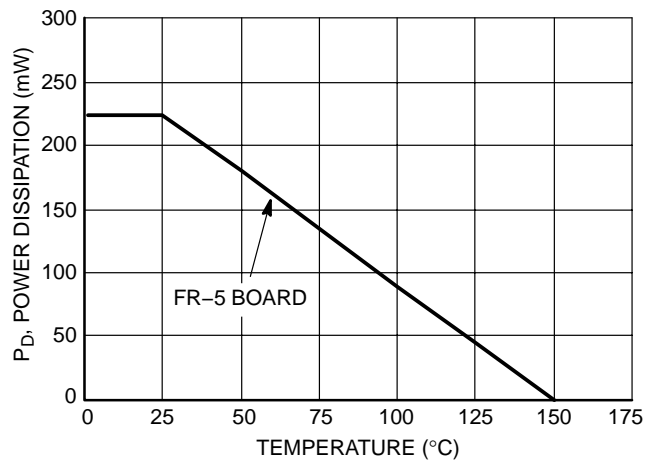
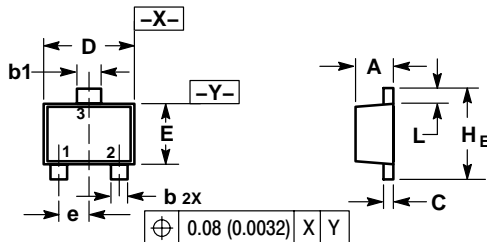


Figure 4. Steady State Power Derating Curve

# μESD3.3DT5G SERIES

## PACKAGE DIMENSIONS

**SOT-723**  
CASE 631AA-01  
ISSUE A



### NOTES:

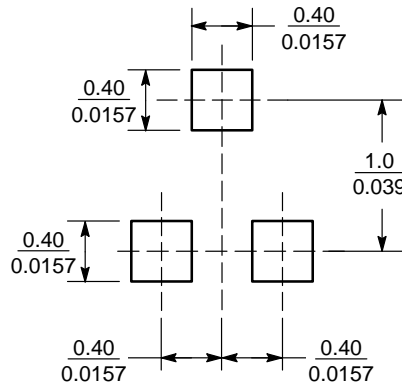
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.20	0.27	0.0059	0.0079	0.0106
b1	0.25	0.3	0.35	0.010	0.012	0.014
C	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.03	0.032	0.034
e	0.40 BSC			0.016 BSC		
H E	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098

### STYLE 4:

- PIN 1. CATHODE  
2. CATHODE  
3. ANODE


## SOLDER FOOTPRINT\*



SCALE 20:1 (mm/inches)

## SOT-723

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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